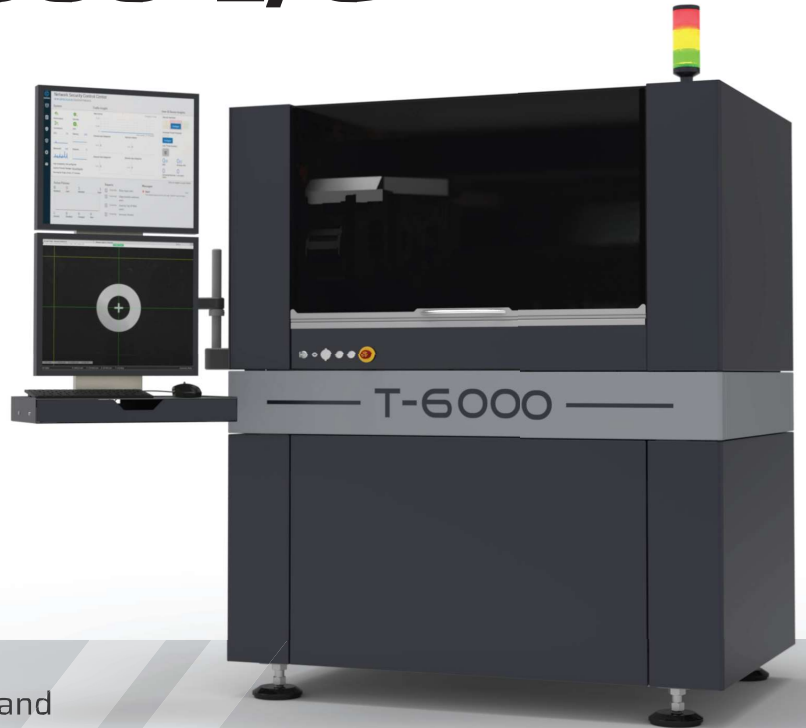


T-6000-L/G

Based on the proven **T-6000-L** series, the DIE bonder **T-6000-L/G** has been further developed. This consists of a stable granite gantry and a high-precision control system for the X, Y and Z axes. The system therefore offers one of the best bonding by performances in the market and is designed for the current and future challenges in the semiconductor industry.



The **T-6000-L/G** guarantees reproducible and accurate results for highly precise placement applications. Optionally, the **T-6000-L/G** can be upgraded with a loading and unloading module to further optimize cycle times and to reduce downtime.

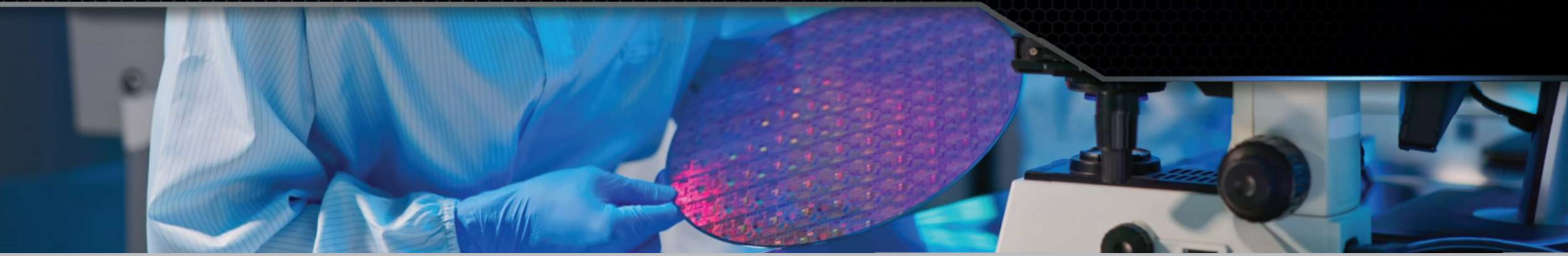
Due to the wide range of process options, the **T-6000-L/G** offers high versatility in combination with speed and high precision. The system can be further expanded at any time with additional options. Thus, our customers receive an individual system tailored to their needs, with which both manual and fully automatic processes can be implemented reliably and effectively. The intuitive software enables simple and easy operation and programming of the system.

This model covers all common connection technologies.

Technical Data

Travel Range with Wafer	400 mm x 410 mm
Wafer Size	2" - 8" (Ring & Frame)
Travel Range w/o Wafer	540 mm x 410 mm
Z-Movement	100 mm
Chip Rotation Max.	up to 360°
Bond Force Range	0.01 N - up to 100 N *
Axis Speed	up to 1.8 m/sec
Placement Accuracy	2,5 µm @ 3 sigma
Axis Resolution	XYZ: 0.01 µm, Theta: 0.01°
Min./Max. Comp. Size	0.05 mm - 100 mm

* Higher bond forces on request



Product Highlights

- Manual mode
- Multichip capable
- Post-bond inspection
- Software programmed temperature control
- Wafermapping
- OCR
- Traceability
- MES
- Automated dispensing needle calibration
- Scrubbing
- Bonding in cavities (15 mm)
- Preform punching

Modules & Options

- Wafer table with DIE ejector
- UV indexer
- WRGB ring light
- Heating plates
- Up to 450 °C
- ΔT ramps up to 60 K/s
- Inert gas
- Automatic tool change
- Various dispensing technologies
- Stamping unit
- Tool heating
- Various feeder widths
- Uplooking camera
- ID Scanner
- DIE flipping unit
- Heated inert gas
- Automatic wafer change
- Magazine feeder
- Inline production
- Formic Acid Module



more information

Bonding Solutions

- Epoxy Bonder
- UV Bonder
- Ultrasonic Bonder
- Thermocompression Bonder
- Sinter Bonder
- Flip Chip Bonder
- Eutectic Bonder
- 3D Bonder
- Photonics Bonder

Applications

- Micro assembly
- Eutectic bonding
- Stamping
- Ultrasonic bonding
- Flip chip bonding
- Thermosonic bonding
- Thermocompression bonding
- Flux dipping
- Epoxy bonding
- DIE stacking

Customized applications

- DTF / DAF bonding
- Multi-DIE bonding
- MEMS
- SMD bonding
- 3D packaging (SiP)
- Laser bar stacking
- Glass bonding
- TO header bonding
- VCSEL bonding
- RFID assembly
- DIE sorting

For more information about our products or services please visit our website.

TRESKY GmbH

Neuendorfstr. 18 B
16761 Hennigsdorf
Germany

+49 3302 86692-0
info@tresky.de
www.tresky.de